Product End-of-Life Disassembly Instructions

Product Category: Monitors and Displays

Marketing Name / Model
[List multiple models if applicable.]

HP EliteDisplay E241e 24-in IPS LED Backlit Monitor

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm IF BD, POWER BD, FK BD</td>
<td>3</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>0</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps Panel</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>Power BD only (C805)</td>
<td>1</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>Displayport cable, D-sub cable, Power cord</td>
<td>3</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1</td>
<td>SCREW DRIVER(PHILLIPS HEAD)</td>
</tr>
<tr>
<td>Description #2</td>
<td>SCREW DRIVER(PHILLIPS HEAD)</td>
</tr>
<tr>
<td>Description #3</td>
<td>SCREW DRIVER(PHILLIPS HEAD)</td>
</tr>
<tr>
<td>Description #4</td>
<td>SCREW DRIVER(HEX HEAD)</td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Take Screw(*4) Off and remove Stand Base From Display Head
2. Remove Rear Cover From Display Head
3. Remove Rubber From Rear Cover
4. Remove Front Cover From Display Head
5. Take Screw(*2) Off From Chassis Cover & Remove Panel
6. Take Screw(*14) Off From P.C.B & Remove Chassis Cover
7. Remove Gasket(*2) From Chassis Cover
8. Take Screw(*3) Off From Front Cover & Remove Function Key P.C.B
9. Remove HP logo and OSD & power Button From Front Cover
10. Take Screw(*4) Off and Remove VESA BKT From Stand
11. Take Screw(*4) Off From Stand and Remove VESA POM and Sharks lift cover from Stand
12. Remove Riser Rear Cover and Cable Cover From Stand
13. Take Screw(*6) Off From Stand Riser BKT and remove Riser Front Cover from Stand
14. Take Screw(*2) Off From Stand BKT and Remove Tilt Cover (left and right) from Stand
15. Remove Arm Rear Cover from Stand Arm BKT
16. Take Screw(*4) from Arm Front Cover and Remove Arm Front Cover
17. Remove Rubber(*8) from Stand Base
18. Take Screw(*8) Off From Base BKT and Remove Base Cover & Space Swivel Cover From Stand Base BKT
19. LCD PANEL EXPLODE

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
HP E241e Disassembly Process

- Kite Hong
- Mechanical RD
- April-13-2014
External Electric Cables Dissecting Process

1. Remove Cable From Display Head.

2. Dissecting To Complete.
Take Screw(*4) Off and remove Stand Base From Display Head

1. Take Screw(*4) Off

2. Remove Stand Base From Display Head.
Remove Rear Cover From Display Head
Remove Rubber From Rear Cover
Remove Front Cover From Display Head

1. Remove Function Key cable Connector

2. Remove Front Cover.
Take Screw(*4) Off From Chassis Cover & Remove Panel

1. Remove AL Foil (x2) from Panel

2. Take Screw(x2) Off from Chassis cover

3. Remove connector off from Panel.

4. Remove the panel.
Take Screw(*14) Off From P.C.B & Remove Chassis cover

1. Take Screw(x14) Off From P.C.B

2. Remove Chassis cover
Remove Gasket From Chassis Cover
Take Screw(*3) Off From Front Cover & Remove Function Key P.C.B

1. Take three Screws Off From Front Cover.
2. Remove keyboard from FC
Remove HP logo and OSD & power Button From Front Cover
Take Screw(*4) Off and Remove VESA BRKT From Stand

1. Take 4 screws off
2. Remove VESA BRKT From Stand
Remove VESA POM and Sharks lift cover from Stand

1. Take Screw(*4) Off From Stand

2. Remove VESA POM and Sharks lift cover from Stand
Remove Riser Rear Cover and Cable Cover From Stand
Remove Riser Front Cover from Stand

1. Take Screw(*6) Off From Stand Riser BKT
2. Remove Riser Front Cover from Stand
Remove Tilt Cover (left and right) from Stand

1. Take Screw(*2) Off From Stand BKT

2. Remove Tilt Cover (left and right) from Stand
Remove Arm Rear Cover from Stand Arm
Remove Arm Front Cover From Stand Arm BKT

1. Take Screw(*4) off from Arm Front Cover

2. Remove Arm Front Cover From Stand Arm BKT
Remove Rubber(*8) from Stand Base
1. Take Screw(*8) Off

2. Remove Base Cover & Space Swivel Cover From Stand Base BKT
1. Loosen C/Shield Screw(*3), Dismantle C/Shield

2. Dismantle C/Top

3. Separate C/Top (push the C/Top because of damages on COF)

4. Separate B/Ass’y
5. Loosen B/L Screw (*5)

6. Dismantle G/Panel

7. Removeal Optical sheets

8. Removeal LGP
LCD PANEL EXPLODE

9. Removal Reflector

10. Separate LED Array from C/Bottom Assy

11. LED Array

Dissecting to complete.
Thank You!